

Serial No. 10/643,919

LISTING OF CLAIMS:

The following listing of claims replaces all previous versions and listings of claims in the present application.

Claims 1-23 (Cancelled)

24. (Currently amended) ~~The~~A method ~~according to claim 22 further of making a printed wiring board~~ comprising:

packing via holes formed in an insulator material with an interlayer conducting material, wherein the interlayer conducting material includes a first metal material and a second metal material, and the second metal material melts at a temperature higher than a predetermined temperature;

stacking layers of the insulator film with conductor patterns to form a stack such that the via holes are located between the conductor patterns in the stack;

forming a solid conductive material in each of the via holes to electrically connect the connector patterns by heating the stack to the predetermined temperature and pressing the stack;

forming the interlayer connecting material as a paste prior to the packing, including adding a solvent to particles made of the metal materials;

adding binder particles to the paste; and

preheating the stack prior to the heating and pressing step and after the packing step to cause the binder particles to diffuse into the metal materials,

wherein:

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the solid conductive material of each via hole includes a unified conductive layer and a solid phase diffusion layer.

the solid phase diffusion layer is formed by the first metal material and a conductor metal, and

the conductor metal is a metal of the associated conductor pattern.

25. (Original) The method according to claim 24 further comprising the step of including a binder metal in the binder particles that melts at a temperature that is lower than that at which the first metal material melts, wherein the preheating heats the stack to a temperature that melts the binder metal, and the binder metal interconnects the first metal material and the second metal material as a result of the preheating.

26. (Original) The method according to claim 24 further comprising the step of employing binder particles that have a particle size of 1-100nm, wherein the first metal material and the second metal material are interconnected by a binder metal, which is included in the binder particles, as a result of the preheating.

27. – 39. (Canceled)